

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3163599

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JAE KEUN HONG	12/23/2014
BEOM HO KIM	12/23/2014
JUN HONG PARK	12/23/2014
KI BO CHANG	12/23/2014
SUNG HUN KIM	12/23/2014
GWANG HWAN LEE	12/23/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAMSUNG SDI CO., LTD.
<b>Street Address:</b>	150-20 GONGSE-RO
<b>Internal Address:</b>	GIHEUNG-GU
<b>City:</b>	YONGIN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	446-902
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14583986
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(704)945-6735
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	704-945-6700
<b>Email:</b>	docket@ahpapatent.com
<b>Correspondent Name:</b>	MELISSA B. PENDLETON
<b>Address Line 1:</b>	11610 N. COMMUNITY HOUSE ROAD
<b>Address Line 2:</b>	SUITE 200
<b>Address Line 4:</b>	CHARLOTTE, NORTH CAROLINA 28277
<b>ATTORNEY DOCKET NUMBER:</b>	7250.009
<b>NAME OF SUBMITTER:</b>	MELISSA B. PENDLETON
<b>SIGNATURE:</b>	/Melissa B. Pendleton/
<b>DATE SIGNED:</b>	12/29/2014

PATENT

**Total Attachments: 4**

source=AssignmentsUSPTO#page1.tif

source=AssignmentsUSPTO#page2.tif

source=AssignmentsUSPTO#page3.tif

source=AssignmentsUSPTO#page4.tif

**RECORDATION FORM COVER SHEET  
PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)**

JAE KEUN HONG  
BEOM HO KIM  
JUN HONG PARK  
KI BO CHANG  
SUNG HUN KIM  
GWANG HWAN LEE

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

**2. Name and address of receiving party(ies)**

Name: Samsung SDI Co., Ltd.

Internal Address: \_\_\_\_\_

Street Address: 150-20 Gongse-ro, Giheung-gu

City: Yongin-si

State: Gyeonggi-do

Country: South Korea

Zip: \_\_\_\_\_

Additional name(s) & address(es) attached? ☐ Yes ☒ No

**3. Nature of conveyance/Execution Date(s):**

Execution Date(s) December 23, 2014

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other \_\_\_\_\_

**4. Application or patent number(s):**

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

14/583,986

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Additon, Higgins & Pendleton, P.A.

Internal Address: \_\_\_\_\_

Street Address: 11610 N. Community House  
Road, Suite 200

City: Charlotte

State: NC

Zip: 28277-2199

Phone Number: 704-945-6700

Fax Number: 704-945-6735

Email Address: \_\_\_\_\_

**6. Total number of applications and patents involved: 1**

**7. Total fee (37 CFR 1.21(h) & 3.41) \$ \_\_\_\_\_**

☐ Authorized to be charged by credit card

☐ Authorized to be charged to deposit account

☐ Enclosed

☐ None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers \_\_\_\_\_

Expiration Date \_\_\_\_\_

b. Deposit Account Number \_\_\_\_\_

Authorized User Name \_\_\_\_\_

**9. Signature: /Melissa B. Pendleton/**

December 29, 2014

Signature

Date

Melissa B. Pendleton

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

## ASSIGNMENT

WHEREAS, I, **Jae Keun HONG**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Beom Ho KIM**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jun Hong PARK**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Ki Bo CHANG**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Sung Hun KIM**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and **Gwang Hwan LEE**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Preparation Method of Thermoplastic Resin Composition and Thermoplastic Resin Composition Prepared Therefrom*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on December 31, 2013, under Serial No. 10-2013-0168918, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Samsung SDI Co., Ltd., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 150-20, Gongse-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-577, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE,

its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

<u>12. 23.</u> , 2014	<u>홍 재 군</u> Jae Keun HONG
<u>12. 23</u> , 2014	<u>김 범 호</u> Beom Ho KIM
<u>12. 23</u> , 2014	<u>박 준 홍</u> Jun Hong PARK
<u>12. 23</u> , 2014	<u>장 기 보</u> Ki Bo CHANG
<u>12. 23</u> , 2014	<u>김 성 훈</u> Sung Hun KIM
<u>12. 23</u> , 2014	<u>이 광 환</u> Gwang Hwan LEE